BCD-to-Seven Segment Latch/Decoder/Driver for Liquid Crystals

The MC14543B BCD-to-seven segment latch/decoder/driver is designed for use with liquid crystal readouts, and is constructed with complementary MOS (CMOS) enhancement mode devices. The circuit provides the functions of a 4-bit storage latch and an 8421 BCD-to-seven segment decoder and driver. The device has the capability to invert the logic levels of the output combination. The phase (Ph), blanking (BI), and latch disable (LD) inputs are used to reverse the truth table phase, blank the display, and store a BCD code, respectively. For liquid crystal (LC) readouts, a square wave is applied to the Ph input of the circuit and the electrically common backplane of the display. The outputs of the circuit are connected directly to the segments of the LC readout. For other types of readouts, such as light-emitting diode (LED), incandescent, gas discharge, and fluorescent readouts, connection diagrams are given on this data sheet.

Applications include instrument (e.g., counter, DVM etc.) display driver, computer/calculator display driver, cockpit display driver, and various clock, watch, and timer uses.

Features

- Latch Storage of Code
- Blanking Input
- Readout Blanking on All Illegal Input Combinations
- Direct LED (Common Anode or Cathode) Driving Capability
- Supply Voltage Range = 3.0 V to 18 V
- Capable of Driving 2 Low–power TTL Loads, 1 Low–power Schottky TTL Load or 2 HTL Loads Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD4056A (with Pin 7 Tied to V_{SS}).
- Chip Complexity: 207 FETs or 52 Equivalent Gates
- Pb-Free Packages are Available*

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Parameter	Symbol	Value	Unit
DC Supply Voltage Range	V_{DD}	-0.5 to +18.0	٧
Input Voltage Range, All Inputs	V _{in}	-0.5 to V_{DD} +0.5	V
DC Input Current per Pin	I _{in}	±10	mA
Power Dissipation per Package (Note 1)	P_{D}	500	mW
Operating Temperature Range	T _A	-55 to +125	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C
Maximum Continuous Output Drive Current (Source or Sink)	I _{OHmax} I _{OLmax}	10 (per Output)	mA
Maximum Continuous Output Power (Source or Sink) (Note 2)	P _{OHmax} P _{OLmax}	70 (per Output)	mW

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C
- 2. $P_{OHmax} = I_{OH} (V_{OH} V_{DD})$ and $P_{OLmax} = I_{OL} (V_{OL} V_{SS})$



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MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648 

SOIC-16 D SUFFIX CASE 751B 

SOEIAJ-16 F SUFFIX CASE 966 A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \ or \ V_{out}) \leq V_{DD}.$

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

TRUTH TABLE

		li	Inputs					Outputs						
LD	ВІ	Ph*	D	С	В	Α	а	b	С	d	е	f	g	Display
Х	1	0	Х	Χ	Χ	Χ	0	0	0	0	0	0	0	Blank
1	0	0	0	0	0	0	1	1	1	1	1	1	0	0
1	0	0	0	0	0	1	0	1	1	0	0	0	0	1
1	0	0	0	0	1	0	1	1	0	1	1	0	1	2
1	0	0	0	0	1	1	1	1	1	1	0	0	1	3
1	0	0	0	1	0	0	0	1	1	0	0	1	1	4
1	0	0	0	1	0	1	1	0	1	1	0	1	1	5
1	0	0	0	1	1	0	1	0	1	1	1	1	1	6
1	0	0	0	1	1	1	1	1	1	0	0	0	0	7
1	0	0	1	0	0	0	1	1	1	1	1	1	1	8
1	0	0	1	0	0	1	1	1	1	1	0	1	1	9
1	0	0	1	0	1	0	0	0	0	0	0	0	0	Blank
1	0	0	1	0	1	1	0	0	0	0	0	0	0	Blank
1	0	0	1	1	0	0	0	0	0	0	0	0	0	Blank
1	0	0	1	1	0	1	0	0	0	0	0	0	0	Blank
1	0	0	1	1	1	0	0	0	0	0	0	0	0	Blank
1	0	0	1	1	1	1	0	0	0	0	0	0	0	Blank
0	0	0	Х	Χ	Χ	Χ	**					**		
†	†	†		†			Inverse of Output					Display		
							1 -	•					as above	

X = Don't care	Χ	= D	on'	t ca	re
----------------	---	-----	-----	------	----

^{† =} Above Combinations

ORDERING INFORMATION

PIN ASSIGNMENT

16 | V_{DD}

15 🛮 f

14] g 13] e

12 d

11] c 10] b

9 🛚 a

LD [1 ●

C [2

B [] 3

D [] 4

A [5 PH [6

BI 🛮 7

V_{SS} [] 8

Package	Shipping [†]
PDIP-16	
PDIP-16 (Pb-Free)	25 Units / Rail
SOIC-16	
SOIC-16 (Pb-Free)	48 Units / Rail
SOIC-16	
SOIC-16 (Pb-Free)	2500 / Tape & Reel
SOEIAJ-16	
SOEIAJ-16 (Pb-Free)	50 Units / Rail
	PDIP-16 PDIP-16 (Pb-Free) SOIC-16 (Pb-Free) SOIC-16 (Pb-Free) SOIC-16 (Pb-Free) SOIC-16 SOIC-16 SOIC-16 SOIC-16 SOIC-16 SOEIAJ-16

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{* =} For liquid crystal readouts, apply a square wave to Ph For common cathode LED readouts, select Ph = 0 For common anode LED readouts, select Ph = 1

 $^{^{**}}$ = Depends upon the BCD code previously applied when LD = 1

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

			- 5	5°C	25°C			125		
Characteristic	Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 3)	Max	Min	Max	Unit
Output Voltage "0" Level $V_{in} = V_{DD}$ or 0	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
$V_{in} = 0$ or V_{DD} "1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage "0" Level (V _O = 4.5 or 0.5 Vdc) (V _O = 9.0 or 1.0 Vdc) (V _O = 13.5 or 1.5 Vdc)	V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	V _{IH}	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	Vdc
Output Drive Current (V_{OH} = 2.5 Vdc) Source (V_{OH} = 4.6 Vdc) (V_{OH} = 0.5 Vdc) (V_{OH} = 9.5 Vdc) (V_{OH} = 13.5 Vdc)	Іон	5.0 5.0 10 10	- 3.0 - 0.64 - - 1.6 - 4.2	- - -	- 2.4 - 0.51 - - 1.3 - 3.4	- 4.2 - 0.88 - 10.1 - 2.25 - 8.8	- - - -	-1.7 -0.36 - -0.9 -2.4	- - - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ Sink $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 9.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	I _{OL}	5.0 10 10 15	0.64 1.6 - 4.2	- - -	0.51 1.3 - 3.4	0.88 2.25 10.1 8.8	- - - -	0.36 0.9 - 2.4	- - -	mAdc
Input Current	I _{in}	15	_	±0.1	_	±0.00001	±0.1	_	±1.0	μAdc
Input Capacitance	C _{in}	-	_	_	_	5.0	7.5	_	-	pF
Quiescent Current (Per Package) $V_{in} = 0$ or V_{DD} , $I_{out} = 0 \mu A$	I _{DD}	5.0 10 15	- -	5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20	- - -	150 300 600	μAdc
Total Supply Current (Note 4, 5) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	I _T	5.0 10 15			$I_{T} = (3$	1.6 μΑ/kHz) f 3.1 μΑ/kHz) f 4.7 μΑ/kHz) f	+ I _{DD}			μAdc

3. Noise immunity specified for worst–case input combination.

Noise Margin for both "1" and "0" level = $1.0 \text{ V} \text{ min } @ \text{ V}_{DD} = 5.0 \text{ V}$ $2.0 \text{ V min } @ \text{V}_{DD} = 10 \text{ V}$ 2.5 V min @ V_{DD} = 15 V

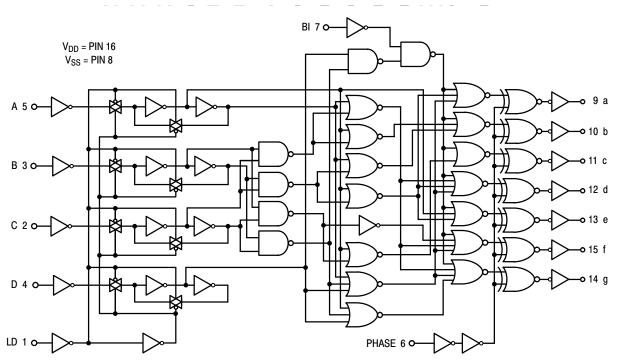
4. To calculate total supply current at loads other than 50 pF: I_T(C_L) = I_T(50 pF) + 3.5 x 10⁻³ (C_L – 50) V_{DD}f where: I_T is in μA (per package), C_L in pF, V_{DD} in V, and f in kHz is input frequency.
 5. The formulas given are for the typical characteristics only at 25°C.

SWITCHING CHARACTERISTICS (Note 6) ($C_L = 50 \text{ pF}, T_A = 25^{\circ}C$)

Characteristic	Symbol	V _{DD}	Min	Тур	Max	Unit
Output Rise Time $t_{TLH} = (3.0 \text{ ns/pF}) C_L + 30 \text{ ns}$ $t_{TLH} = (1.5 \text{ ns/pF}) C_L + 15 \text{ ns}$ $t_{TLH} = (1.1 \text{ ns/pF}) C_L + 10 \text{ ns}$	t _{TLH}	5.0 10 15	- - -	100 50 40	200 100 80	ns
Output Fall Time $t_{THL} = (1.5 \text{ ns/pF}) \text{ C}_{L} + 25 \text{ ns} \\ t_{THL} = (0.75 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns} \\ t_{THL} = (0.55 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns}$	t _{THL}	5.0 10 15	- - -	100 50 40	200 100 80	ns
Turn–Off Delay Time $t_{PLH} = (1.7 \text{ ns/pF}) C_L + 520 \text{ ns}$ $t_{PLH} = (0.66 \text{ ns/pF}) C_L + 217 \text{ ns}$ $t_{PLH} = (0.5 \text{ ns/pF}) C_L + 160 \text{ ns}$	t _{PLH}	5.0 10 15	- - -	605 250 185	1210 500 370	ns
Turn–On Delay Time $t_{PHL} = (1.7 \text{ ns/pF}) \text{ C}_{L} + 420 \text{ ns} \\ t_{PHL} = (0.66 \text{ ns/pF}) \text{ C}_{L} + 172 \text{ ns} \\ t_{PHL} = (0.5 \text{ ns/pF}) \text{ C}_{L} + 130 \text{ ns}$	t _{PHL}	5.0 10 15	- - -	505 205 155	1650 660 495	ns
Setup Time	t _{su}	5.0 10 15	350 450 500		- - -	ns
Hold Time	t _h	5.0 10 15	40 30 20		- - -	ns
Latch Disable Pulse Width (Strobing Data)	t _{WH}	5.0 10 15	250 100 80	125 50 40	- - -	ns

^{6.} The formulas given are for the typical characteristics only.

LOGIC DIAGRAM



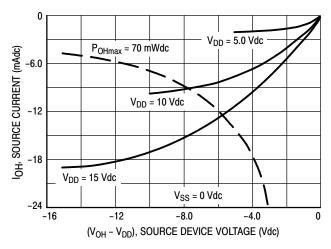


Figure 1. Typical Output Source Characteristics

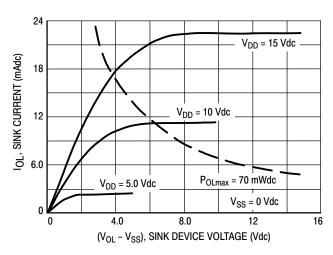
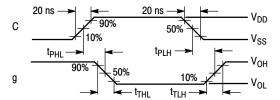
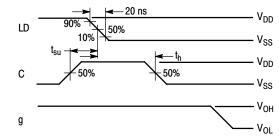


Figure 2. Typical Output Sink Characteristics

(a) Inputs D, Ph, and BI low, and Inputs A, B, and LD high.



-(b) Inputs D, Ph, and BI low, and Inputs A and B high.



(c) Data DCBA strobed into latches

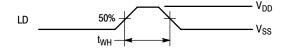


Figure 4. Dynamic Signal Waveforms

Inputs BI and Ph low, and Inputs D and LD high. f in respect to a system clock.

All outputs connected to respective C_L loads.

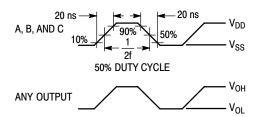
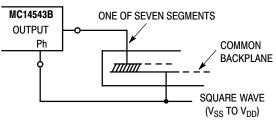


Figure 3. Dynamic Power Dissipation Signal Waveforms

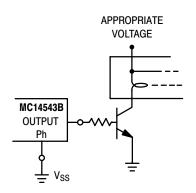
CONNECTIONS TO VARIOUS DISPLAY READOUTS

LIQUID CRYSTAL (LC) READOUT

EIGOD ONTO INE (EO) NEMBOOT

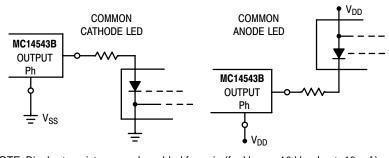


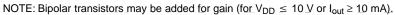
INCANDESCENT READOUT

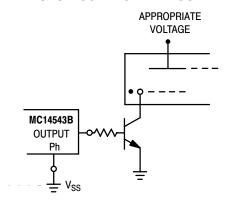


LIGHT EMITTING DIODE (LED) READOUT

GAS DISCHARGE READOUT







CONNECTIONS TO SEGMENTS

$$f / \frac{a}{g} / b$$

 $e / \frac{d}{g} / c$

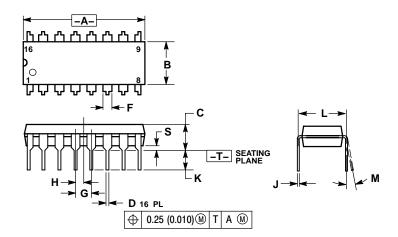
$$V_{DD} = PIN 16$$

 $V_{SS} = PIN 8$



PACKAGE DIMENSIONS

PDIP-16 CASE 648-08 **ISSUE T**

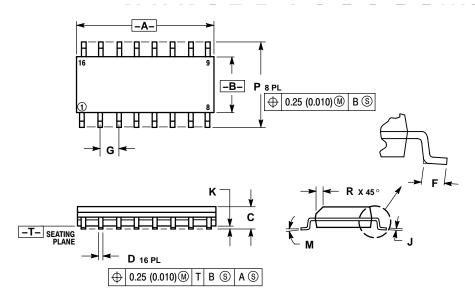


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD ELACH
- MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS		
DIM	MIN	MIN MAX		MAX		
Α	0.740	0.770	18.80	19.55		
В	0.250	0.270	6.35	6.85		
С	0.145	0.175	3.69	4.44		
D	0.015	0.021	0.39	0.53		
F	0.040	0.70	1.02	1.77		
G	0.100	BSC	2.54 BSC			
Н	0.050	BSC	1.27 BSC			
J	0.008	0.015	0.21	0.38		
K	0.110	0.130	2.80	3.30		
L	0.295	0.305	7.50	7.74		
М	0°	10 °	0 °	10 °		
S	0.020	0.040	0.51	1.01		

SOIC-16 CASE 751B-05 **ISSUE J**



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

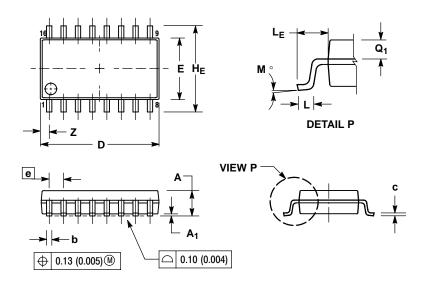
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- PER SIDE.

 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES				
DIM	MIN	MAX	MIN	MAX			
Α	9.80	10.00	0.386	0.393			
В	3.80	4.00	0.150	0.157			
C	1.35	1.75	0.054	0.068			
D	0.35	0.49	0.014	0.019			
F	0.40	1.25	0.016	0.049			
G	1.27	BSC	0.050 BSC				
J	0.19	0.25	0.008	0.009			
K	0.10	0.25	0.004	0.009			
M	0°	7°	0°	7°			
Р	5.80	6.20	0.229	0.244			
R	0.25	0.50	0.010	0.019			

PACKAGE DIMENSIONS

SOEIAJ-16 CASE 966-01 ISSUE A



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS D AND E DO NOT INCLUDE
 MOLD FLASH OR PROTRUSIONS AND ARE
 MEASURED AT THE PARTING LINE. MOLD FLASH
 OR PROTRUSIONS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.

 TERMINAL NUMBERS ARE SHOWN FOR
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 THE LEAD WIDTH DIMENSION (b) DOES NOT
- 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α		2.05		0.081		
A ₁	0.05	0.20	0.002	0.008		
b	0.35	0.50	0.014	0.020		
C	0.10	0.20	0.007	0.011		
D	9.90	10.50	0.390	0.413		
E	5.10	5.45	0.201	0.215		
е	1.27	BSC	0.050 BSC			
HE	7.40	8.20	0.291	0.323		
L	0.50	0.85	0.020	0.033		
LE	1.10	1.50	0.043	0.059		
M	0 °	10 °	0 °	10°		
Q1	0.70	0.90	0.028	0.035		
Z		0.78		0.031		

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